

EV Group Launches Step-and-Repeat Mastering Services for Nanoimprint Lithography – June 23, 2021

semiconductor packaging news

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June 23, 2021

[Is the US Chip Wall Starting to Crumble?](#)

"Failure is not an option" is an epic phrase associated with Gene Kranz and the Apollo 13 Moon landing mission, which went terribly wrong, but ended happily thanks to some Mission Control heroics. Likewise, with a newly-appointed vice premier at the microchip helm, China is leaving itself no more excuses to fail. The nation's decision to anoint a "chip czar" is the latest step to advance its semiconductor ...

Asia Times



[Full automation bond testers](#)

A Sigma eliminates human error and comes with game-changing automation capabilities, robotic handlers, and smart vision cameras for operator-free bond testing and analysis. Learn more. xyztec



[Prevent Costly Die Migration.](#)

Avoid the high costs associated with die migration from the pockets of chip trays with Gel-Pak's New LCS2™ Waffle Pack Lid. Learn more. Gel-Pak, a Division of Delphon



[GlobalFoundries invests US\\$4bn in Singapore fab](#)

GlobalFoundries Inc plans to build a US\$4 billion chipmaking plant in Singapore that is scheduled to start in 2023, choosing Asia for the site of its latest expansion, ...

Taipei Times

[Removing Underfill for Analysis of 2.5D Modules Using CF4-Free Microwave Induced Plasma](#)

Selective removal of underfill on a 2.5D package to enable subsequent analysis on interposer interconnects and Cu μbumps in cross-section using artifact-free ...

Technical Paper

[North American Semiconductor Equipment Industry Posts May 2021 Billings, Extends Record Streak](#)

North America-based semiconductor equipment manufacturers posted \$3.59 billion in billings worldwide in May 2021, according to the May Equipment Market Data ...

SEMI

Technical Papers

- [Will an Adhesion Promoter Prevent Delamination in Power Semiconductor Packages?](#)
- [Innovations in Wire Bond Inspection](#)
- [Customized Assembly Process for Hermetic Devices](#)
- [CF4-free Microwave Induced Plasma Decapsulation of Automotive Semiconductor Devices](#)
- [Optimizing Insertion Extraction Force in a Pin-Socket Interconnect](#)
- [Hermetic Package Process Development](#)
- [Justifying the Purchase of Die or Wire Bonding Equipment](#)

[Maskless Exposure for Adv Packaging](#)

This paper examines how maskless exposure technology overcomes limitations of traditional lithography in back-end processing, providing unsurpassed flexibility, scalability and CoO benefits. EV Group



[NanoResolution MRS™ Sensor](#)

Increase throughput with the NanoResolution MRS™ Sensor that is 2-3X faster, delivering greater than 25 wafers (300mm) per hour. Learn more. CyberOptics Corporation



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Press Releases

[EV Group Launches Step-and-Repeat Mastering Services for Nanoimprint Lithography](#)

EV Group announced that it has established the EVG Step-and-Repeat (S&R) Mastering Shop, a new service offering to help customers accelerate the deployment of nanoimprint ...

EV Group

[Hitachi High-Tech Launches AFM100 and AFM100 Plus Atomic Force Microscopes](#)

Hitachi High-Tech Corporation announced the launch of both AFM100 and AFM100 Plus systems - entry-level and intermediate-level models of Hitachi's compact and versatile ...

Hitachi High-Tech Corporation

[STMicroelectronics and Lumentum benefit the most in Apple's supply chain. Who's next?](#)

"In mobile markets there is a temporary hiatus in growth of 3D sensing due to the ban of Huawei in the US as well as the fact that the Android camp has abandoned the technology." ...

Yole Développement

[Meyer Burger secures debt financing for further expansion of cell and module capacity](#)

The loan agreement for EUR 125 million with a syndicate led by Ostsächsische Sparkasse Dresden, Germany was signed on June 15, 2021. Further lenders include a group of savings ...

[MEMS Semiconductors Strengthen After Holding Up Well in 2020](#)

Sales of semiconductor sensors and actuators made with microelectromechanical systems (MEMS) technology are expected to grow about 16% in 2021 to a record-high ...

IC Insights

[Microchip Boosts GaN-on-SiC with MMIC for Satellite and 5G](#)

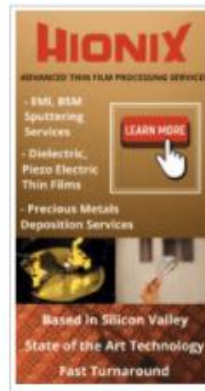
Modern satellite systems are based on geostationary constellations that offer excellent coverage of the earth's surface and fast broadband data transmission. Leveraging ...

EE Times

[Physicists uncover secrets of world's thinnest superconductor](#)

Physicists from across three continents report the first experimental evidence to explain the unusual electronic behavior behind the world's thinnest superconductor, ...

MIT News



[A Beginner's Guide to Topological Materials](#)

Ever since a new class of materials called topological insulators was first created--a discovery that helped win the Nobel Prize in Physics in 2016--researchers have been ...

IEEE Spectrum

[Component shortage to persist, PC vendors say](#)

Major PC vendors expect a shortage of key components to last another 12 months until the second quarter of next year, when PC demand wanes after two years of ...

Taipei Times

[Supply chain resilience touted at forum](#)

Supply chain resilience must be boosted for the semiconductor and other industries, representatives said at a virtual forum on tech supply chain partnerships, ...

Taipei Times



[Manufacturing Bits: June 22](#)

At the recent 2021 IEEE 71st Electronic Components and Technology Conference (ECTC), the Institute of Microelectronics of the Chinese Academy of Sciences ...

Semiconductor Engineering

Meyer Burger Technology Ltd

[Breakthrough for Fan-In, Fan-Out WLPs](#)

Anhydride-free liquid compression molding material addresses the stability, handling, protection, and thin dimensional challenges of new packaging techniques. Learn more.



Henkel Corporation

[Quote of the Day](#)

"Genius is born--not paid."

Oscar Wilde

[Breakthrough for Fan-In, Fan-Out WLPs](#)

Anhydride-free liquid compression molding material addresses the stability, handling, protection, and thin dimensional challenges of new packaging techniques. Learn more.



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Kyzen Corporation

[What Year Was It?](#)

[Texas Votes to Join USA](#)

The Congress of the Republic of Texas votes to join the United States of America.

The day was Jun 23. What year was it?



[Smart Passivation Shear — The Most Reliable Way of Testing](#)

Passivation layers can cause difficulties during quality control testing of interconnects, learn how they can be overcome. Read more.



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Cartoon of the Day



"We need to make room for the new hires. We're moving you to the cloud."
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Calendar

- [Jun 23, 2021: IMAPS New England Annual Meeting](#)
- [Jun 23, 2021: ECTC Virtual Conference](#)
- [Jun 28, 2021: Overview of Semiconductor Manufacturing Webinar for Asian Attendees](#)
- [Jul 1, 2021: Webinar: What's ahead for Semiconductor Packaging?](#)

Ultrasonic/Thermosonic Bonding Paper
 Ultrasonic power is introduced during thermocompression bonding to perform die bonding at low temperature & pressure. Paper identifies processes to improve thermosonic bonding. Read more.
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AI Technology, Inc.



Test Your Knowledge Answer
 What color is an airplanes black box (recorder)?
 Answer: Orange. The term "black box" is almost never used within the flight safety industry or aviation, which prefers the term "flight recorder". The recorders are not permitted to be black in color, and must be bright orange, as they are intended to be spotted and recovered after incidents.

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